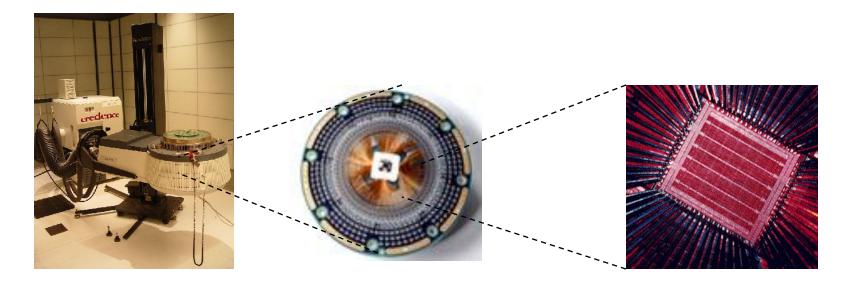
Design For Test





Introduction

- Chip test needed after manufacturing so as to determine which parts are free of manufacturing defects
 - Goal is to discover manufacturing defects, not design bugs
 - Done before wafer dicing







Chip test

- Goal:
 - Have a very high probability of finding manufacturing defects
 - Caused by: dust particles, fab control problems
 - Examples: Opens, shorts, transistors/wires out of specs
 - While minimizing the cost of finding the defects





Chip Test and Cost

- Cost of test adds up to 40% to the cost of building the chip
- However, the cost of releasing a defective chip is very high
 - Packaging; Distribution; managing part return;
 - Reduction in customer satisfaction





Chip Test Methods

- Dominant Method:
 - Scan Testing using stuck-at fault model
- Secondary Method:
 - Built In Self Test (BIST)





Fault Models

- Need a fault model so that a simulator can be used to determine the impact of a potential fault
 - i.e. Use the simulator to determine how to detect that fault
- Actual faults are mainly shorts and opens
 - Difficult and messy to model and simulate
- In practice using the stuck-at fault model captures the vast majority of "real" faults
 - i.e. Fault = Stuck-At-0 or Stuck-At-1

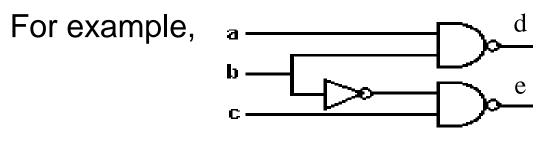




Using Stuck-At faults

Objectives:

- To sensitize and propagate faults to scanned outputs.
- To achieve high fault coverage (% of potential faults that are detectable)
- with fewest possible input choices



What are the test vectors that will <u>sensitize</u> a S-A-0 at d?

What test vector will propagate S-A-0 at d to e?





D-algorithm

(+ its extensions)

- Determines reasonably minimum test vector set that can detect a very high percentage of SA-0 and SA-1 faults at the outputs of the circuit
- % of faults detected = <u>fault coverage</u>





Test Vectors

- Generate test vectors that sensitize and propagate internal faults to outputs
 - Observe outputs to determine if the results are correct or not
- Do you expect all faults to be discoverable from the chip I/O only?

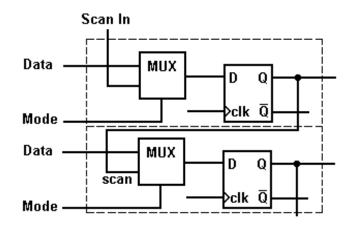




Synchronous Logic Under Normal Mode of Operation:



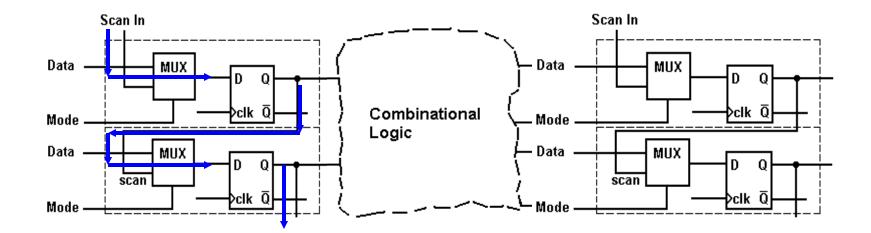
Replace Register Cells with Scan Cell:







Test Mode of Operation

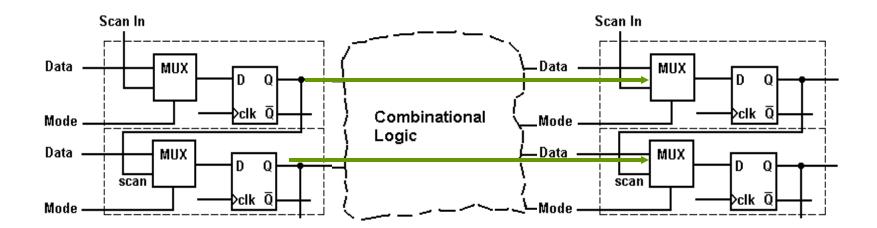


Step 1 : Scan in test vector





Test Mode of Operation

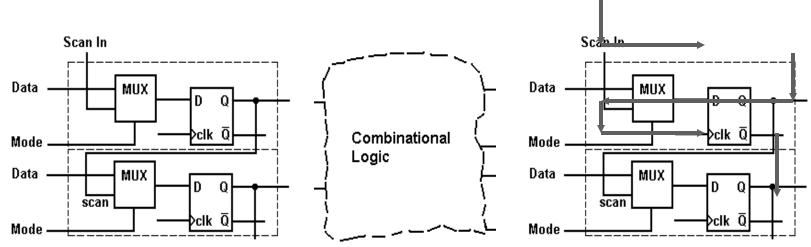


Step 2 : Operate for one clock cycle





Test Mode of Operation



Step 3 : Scan out result vector

- Permits testing of all combinational logic in a design.
 - Flip-flops tested through the scan chain itself





Test Quality

Test Escape

It can be shown that the percentage of parts that are still faulty but are not detected as being faulty, is given as 1^{1} :

$$TE = 1 - Y^{(1 - T)}$$

where TE is the test escape, T is fault coverage, Y is the yield.

For example, for Y = 50% and T = 95%, what is the test escape?

Typically, using the verification vectors (from your Verilog test fixture) for test gives a 80% coverage. What is the test escape then?

Typically, fault coverages above 99% give acceptably low test escapes.

Source: Williams and Brown ("Defect level as a function of fault coverage," IEEE Trans Comp., C-30(12), December 1981, pp. 987-988.





Partial Scan

Full Scan:

• Every flip-flop is included in a scan chain (generally several scan chains on the chip)

Partial Scan:

- Some flip-flops left out
- Works best on synchronous circuits without feedback
 - i.e. Excluded flip-flops treated as pass-through with a single cycle delay





Memory Testing

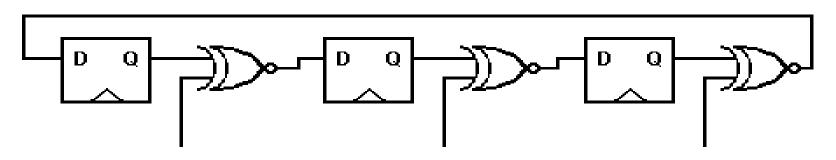
- Memories are exhaustively tested.
- Memories are tested for opens, shorts at individual locations and shorts between neighboring locations by marching test patterns through them.
- Memories are isolated by scan registers for testing purposes.





Built-In Self Test (BIST)

- In the most common BIST approach, the scan cells are modified to generate pseudorandom test vectors at the input to a logic block, and then to collect a signature at the output (using a linear feedback shift register).
- BIST takes more silicon area and more cycles (as pseudorandom) but saves on the cost of generating and storing test vectors.
- Also often takes less elapsed time as can often be run at full clock rate
- Automatic CAD support starting to appear

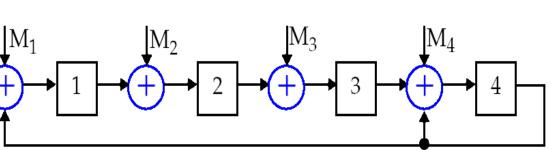






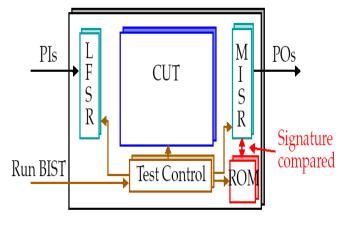
BIST

- LFSR:
 - Linear Feedback Shift Register
 - Used to generate pseudo-random sequence
- MISR
 - Multiple Signature Input Register
 - Used to generate signature of tested circuit





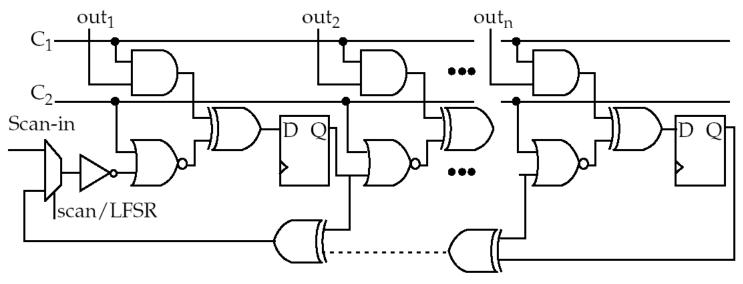
Synopsys University Courseware 2008 Synopsys, Inc. Lecture - 10 Developed By: Paul D. Franzon



NC STATE UNIVERSITY

BILBO

- Built-In Logic Block Observer:
 - Incorporates BIST into a scan architecture



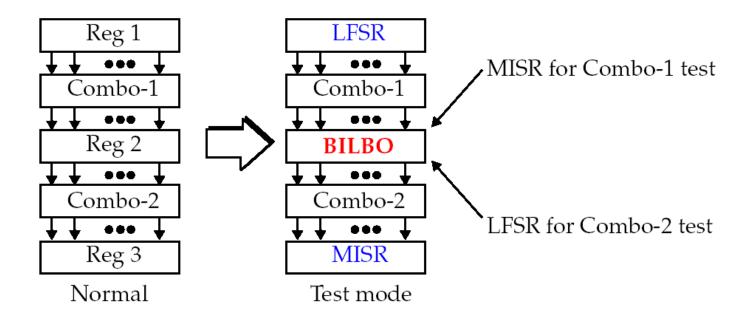
C₁ and C₂ configure as a **shift register** for scan (00), an **LFSR** (00), **MISR** (10) a **Normal** (11).





BILBO

- Scan-out signatures from BILBO registers after being configured as MISRs
 - Compare with expected result







Scan DFT in the Synopsys Environment

Sample Synopsys script with a concentration on DFT. (Please see the tutorial [available in Iview] and manual for more details.)

read -f Verilog fsm.v link_library = target_library = lsi_10k.db create_clock clock81 -period 12.3

/* must expand design and click on clock81 first */ set_input_delay -clock clock81 -max -rise 2 "RW" set_test_methodology full_scan

/* menu: attributes -> optimize directives -> design */
set_scan_style multiplexed_flip_flop

/* compile including scan */ compile map_effort low





Scan DFT in the Synopsys Environment

/* check for testability analysis -- look at result */ insert_test check_test

/* create test patterns to check for ATPG conflicts (additional option in */ /* create pattern menu), also checks fault coverage */ create_test_patterns -sample 5

/* full test pattern creation and scan insertion are done complete chip at */ /* the end but try them if you want */ insert_test -scan_chains 1 create_test_patterns -output fsm.vdb \ -compaction_effort low \ -check_contention_float true -backtrack_effort low \ -random_pattern_failure_limit 64 -sample 100





Speed-Related Defects

Emerging Issue in DFT:

- "Delay faults" becoming more common with high-speed designs
 - i.e. Fault model = extra delay
- Delay faults not normally detected in scan-based testing
 - ATPG equipment usually run at slow speed
- BIST can detect delay faults





Speed Related Defects

Detection using scan requires:

- Test vectors that sensitize and propagate delay faults (preferably – to get high coverage of delay faults)
- At-speed automatic testing
 - At least test cycle has to be run at normal clock period





Summary

- What is the purpose of DFT?
- What is the purpose of a fault model?
- What fault model is usually used?
- What is the value of scan based testing?



